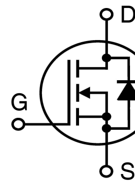
IXYS

X-Class HiPerFET™ Power MOSFET

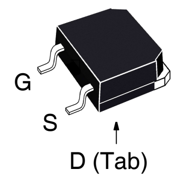
IXFT32N100XHV
IXFH32N100X
IXFK32N100X

V_{DSS} = 1000V
I_{D25} = 32A
$R_{DS(on)} \leq$ 220mΩ

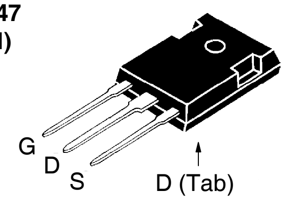
N-Channel Enhancement Mode
Avalanche Rated



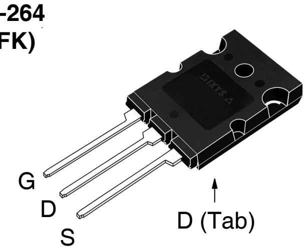
TO-268HV (IXFT..HV)



TO-247 (IXFH)



TO-264 (IXFK)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	1000	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	1000	V
V_{GSS}	Continuous	±30	V
V_{GSM}	Transient	±40	V
I_{D25}	T_C = 25°C	32	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	64	A
I_A	T_C = 25°C	16	A
E_{AS}	T_C = 25°C	2	J
dv/dt	$I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq$ 150°C	50	V/ns
P_D	T_C = 25°C	890	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
M_d	Mounting Torque (TO-247 & TO-264)	1.13 / 10	Nm/lb.in
Weight	TO-268HV	4	g
	TO-247	6	g
	TO-264	10	g

Features

- International Standard Packages
- Low $R_{DS(ON)}$ and Q_G
- Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 1mA	1000			V
$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 4mA	3.5		6.0	V
I_{GSS}	V_{GS} = ±30V, V_{DS} = 0V			±100	nA
I_{DSS}	V_{DS} = V_{DSS}, V_{GS} = 0V			50	µA
	T_J = 125°C			3	mA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 0.5 • I_{D25}, Note 1			220	mΩ

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max	
g_{fs}	V_{DS} = 20V, I_D = 16A, Note 1	14	23		S
R_{Gi}	Gate Input Resistance		0.6		Ω
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		4075		pF
C_{oss}			520		pF
C_{rss}			10		pF
	Effective Output Capacitance				
$C_{o(er)}$	Energy related; V_{GS} = 0V, V_{DS} = 0.8 • V_{DSS}		140		pF
$C_{o(tr)}$	Time related		585		pF
$t_{d(on)}$	**Resistive Switching Times** V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}, R_G = 2Ω (External)		29		ns
t_r			12		ns
$t_{d(off)}$			80		ns
t_f			12		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		130		nC
Q_{gs}			27		nC
Q_{gd}			70		nC
R_{thJC}				0.14	°C/W
R_{thCS}	TO-247		0.21		°C/W
	TO-264P		0.15		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max	
I_S	V_{GS} = 0V			32	A
I_{SM}	Repetitive, pulse Width Limited by T_{JM}			128	A
V_{SD}	$I_F = I_S$, V_{GS} = 0V, Note 1			1.4	V
t_{rr}	I_F = 16A, -di/dt = 100A/μs, V_R = 100V		200		ns
Q_{RM}			1.5		μC
I_{RM}			15		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

Fig. 1. Output Characteristics @ $T_J = 25^oC$

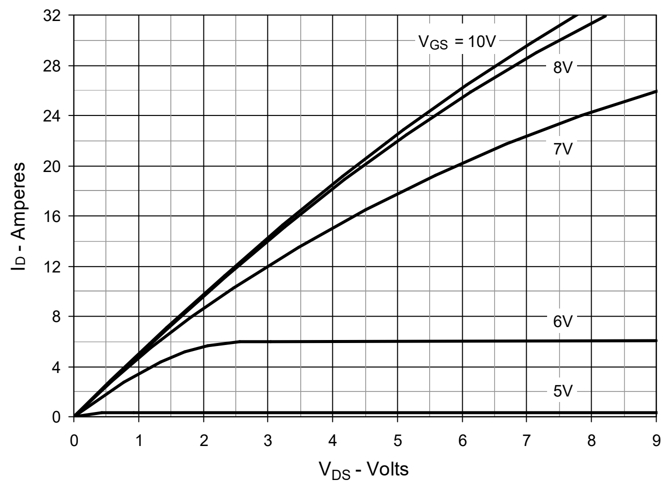


Fig. 2. Extended Output Characteristics @ $T_J = 25^oC$

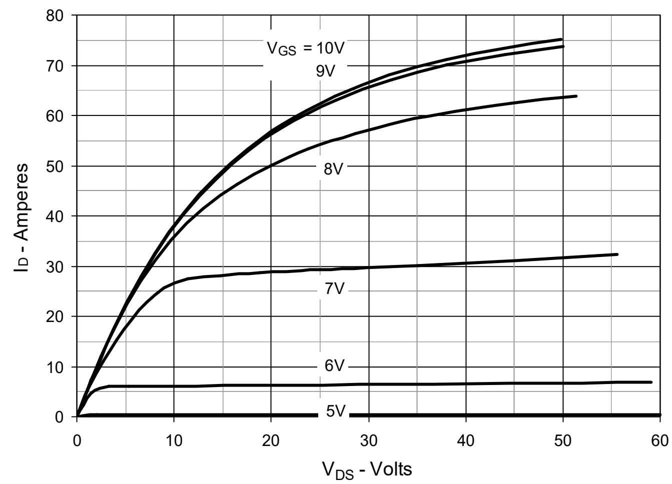


Fig. 3. Output Characteristics @ $T_J = 125^oC$

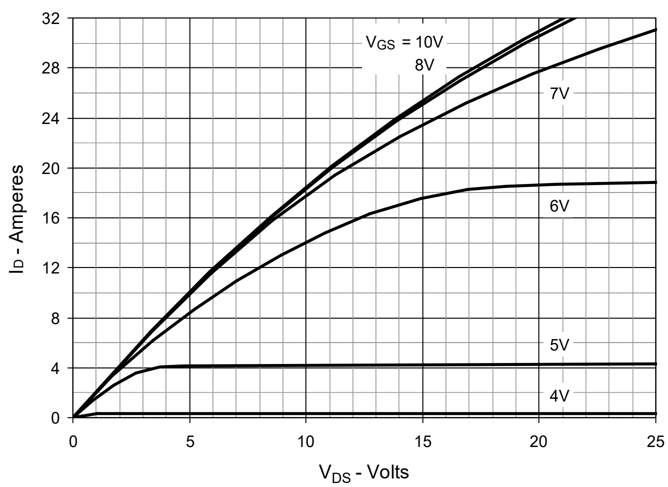


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 16A Value vs. Junction Temperature

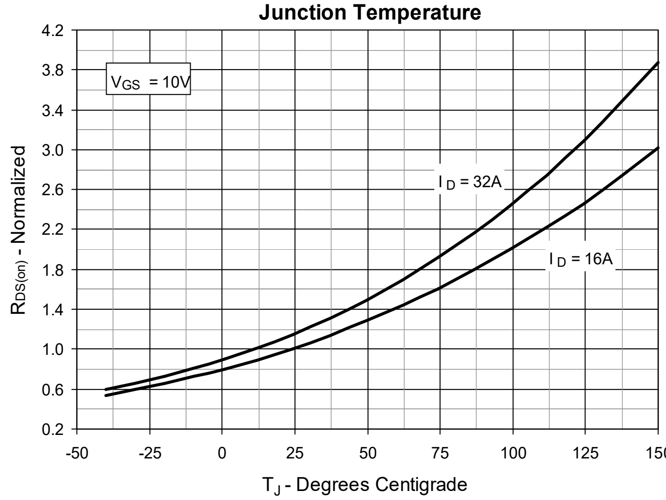


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 16A Value vs. Drain Current

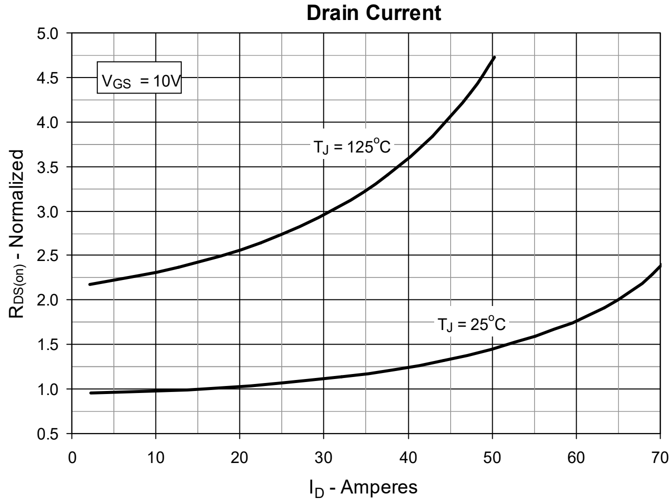


Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature

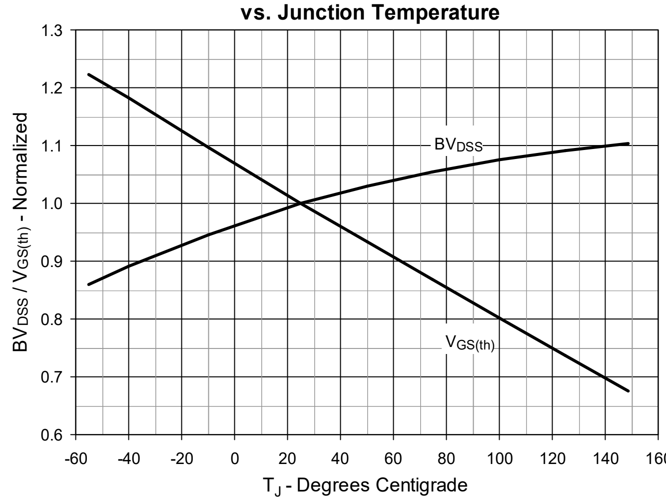


Fig. 7. Maximum Drain Current vs. Case Temperature

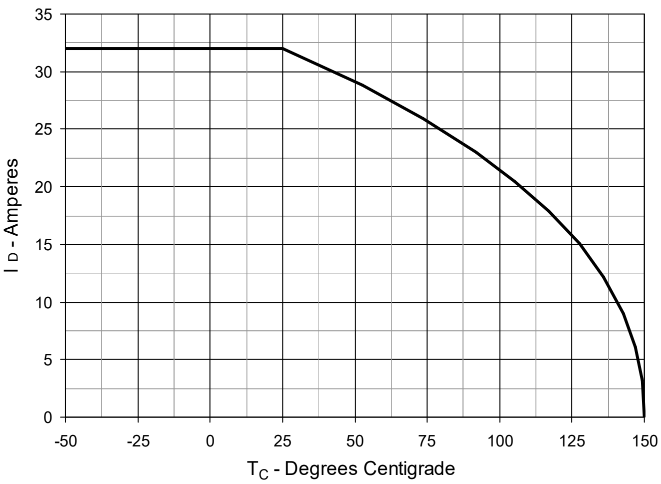


Fig. 8. Input Admittance

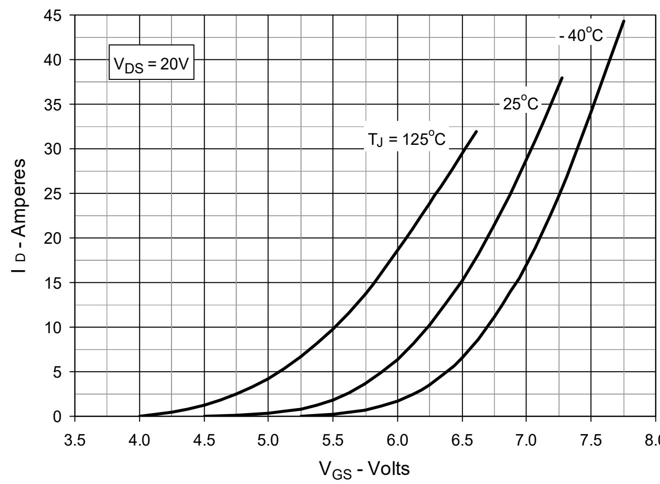


Fig. 9. Transconductance

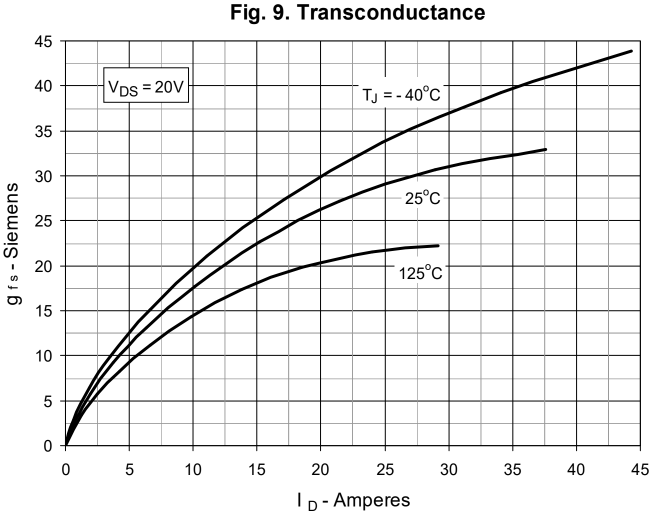


Fig. 10. Forward Voltage Drop of Intrinsic Diode

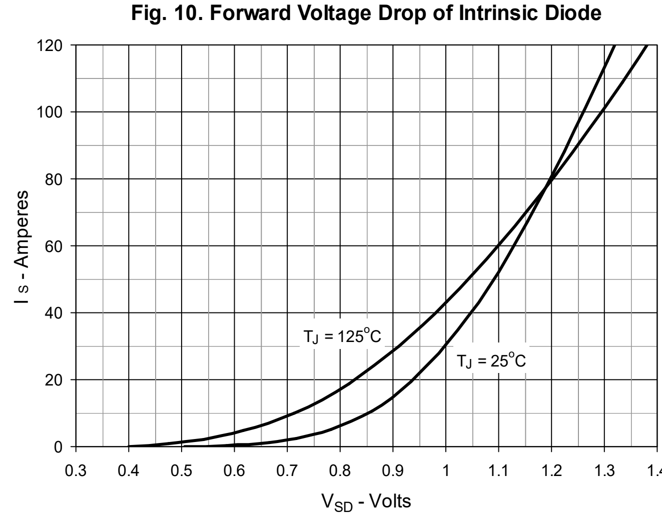


Fig. 11. Gate Charge

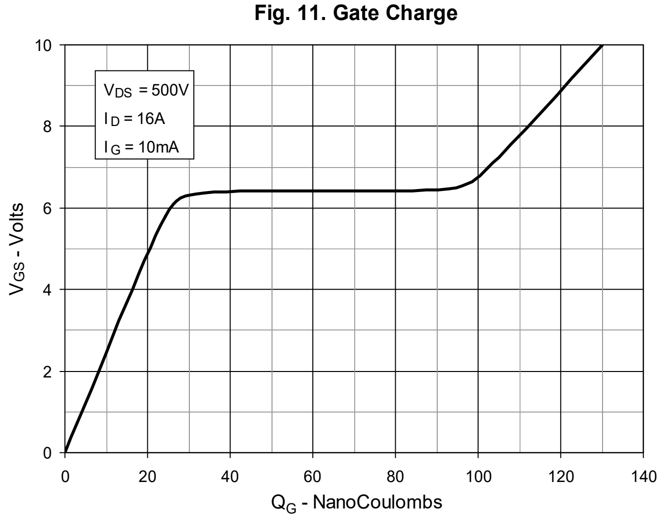


Fig. 12. Capacitance

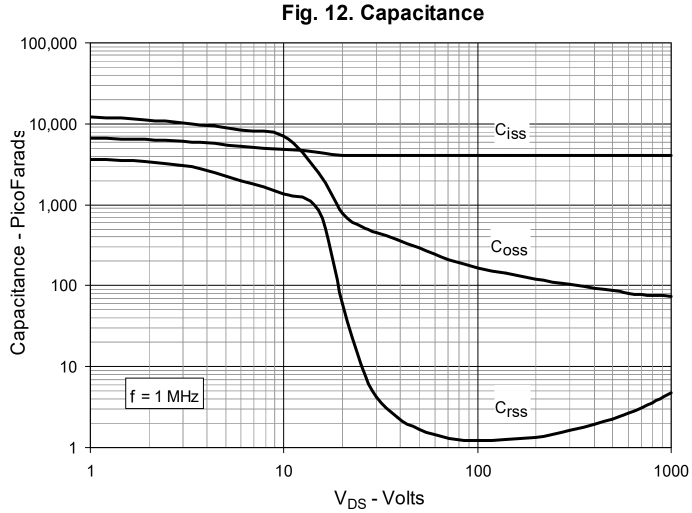


Fig. 13. Output Capacitance Stored Energy

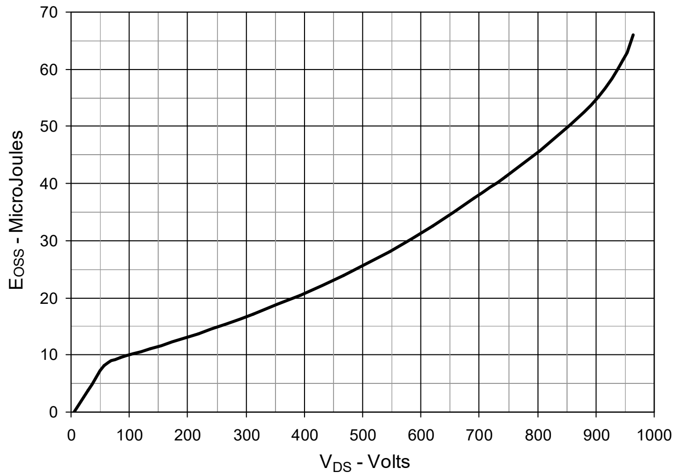


Fig. 14. Forward-Bias Safe Operating Area

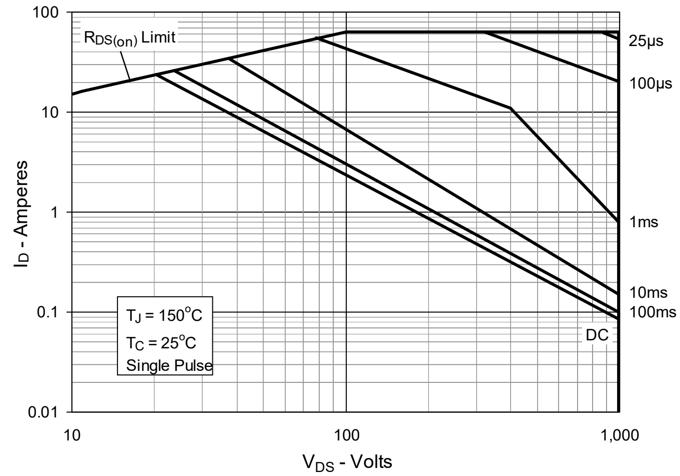
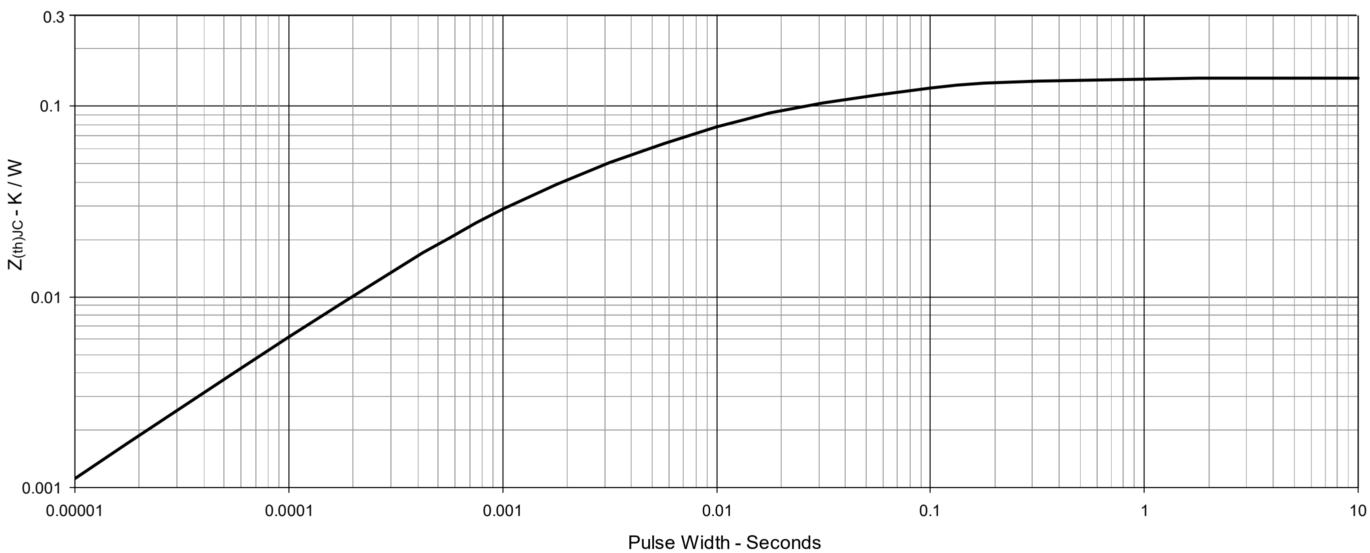
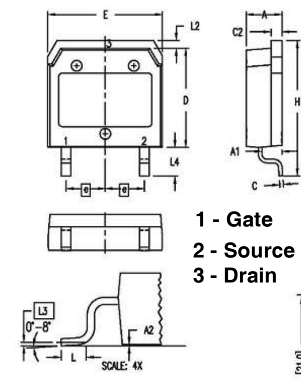
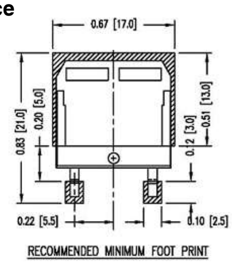


Fig. 15. Maximum Transient Thermal Impedance



TO-268HV Outline



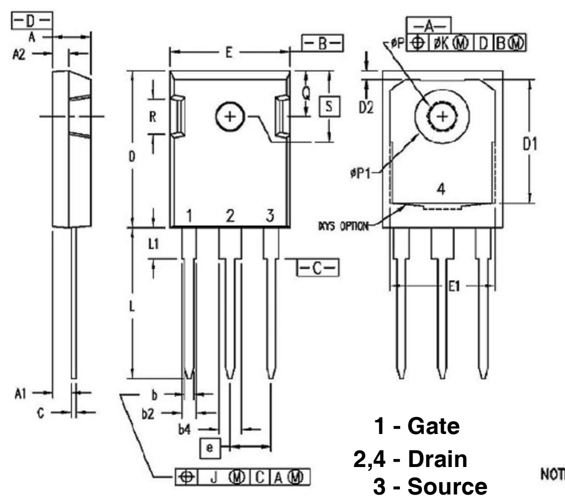


CREEPAGE DISTANCE			
DESCRIPTION	SYMBOL	MIN DISTANCE	
LEAD TO LEAD AIR CLEARANCE	e2	0.372"	9.45mm
LEAD TO LEAD PKG SURFACE CREEPAGE	e2	0.374"	9.50mm
LEAD TO BOTTOM DRAIN CREEPAGE	A1+D3	0.213"	5.40mm

SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.465	.476	11.80	12.10
D2	.295	.307	7.50	7.80
D3	.114	.126	2.90	3.20
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
(e2)	.374	.386	9.50	9.80
H	.736	.752	18.70	19.10
L	.067	.079	1.70	2.00
L2	.039	.045	1.00	1.15
L3	.010 BSC		0.25 BSC	
L4	.150	.161	3.80	4.10

NOTE:
1. This drawing meets all dimensions requirement of JEDEC outlines TO-268AA except L dimension.
2. All metal surface are matte pure tin plated except trimed area.
3. L3 is Gauge plane to measure L.
4. These dimension do not include mold flash and they will not exceed 0.005[0.13] per side.

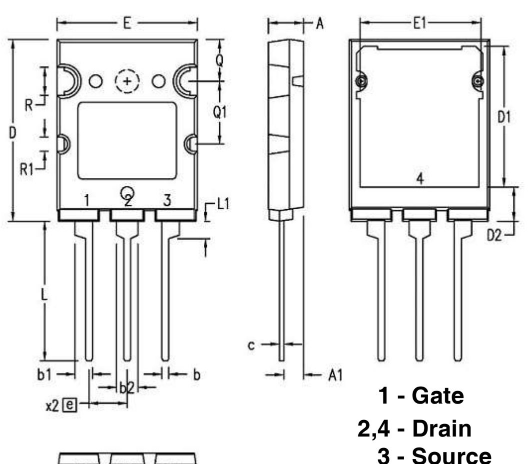
TO-247 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.087	1.91	2.20
b4	.115	.126	2.92	3.20
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
D1	.650	.690	16.51	17.53
D2	.035	.050	0.89	1.27
E	.620	.635	15.75	16.13
E1	.545	.565	13.84	14.35
e	.215 BSC		5.45 BSC	
J	--	.010	--	0.25
K	--	.025	--	0.64
L	.780	.810	19.81	20.57
L1	.150	.170	3.81	4.32
ØP	.140	.144	3.55	3.65
ØP1	.275	.290	6.99	7.37
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.242 BSC		6.15 BSC	

NOTE: This drawing will meet all dimensions requirement of JEDEC outlines TO-247 AD (R-PSIP-F3)

TO-264 Outline



NOTE: Leads and back heatsink are Matte Pure Tin plated.

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.209	4.70	5.30
A1	.102	.118	2.60	3.00
b	.035	.049	0.90	1.25
b1	.091	.106	2.30	2.70
b2	.110	.126	2.80	3.20
c	.020	.033	0.50	0.85
D	1.012	1.035	25.70	26.30
D1	.783	.799	19.90	20.30
D2	.185	.205	4.70	5.20
E	.776	.799	19.70	20.30
E1	.661	.677	16.80	17.20
e	.215 BSC		5.46 BSC	
L	.768	.807	19.50	20.50
L1	.091	.106	2.30	2.70
Q	.228	.244	5.80	6.20
Q1	.346	.362	8.80	9.20
ØR	.150	.165	3.80	4.20
ØR1	.071	.087	1.80	2.20

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